

Features

- Ultra small mold type.
- Low VF
- High reliability

Mechanical Data

- Case: SOD-723 Standard package, molded plastic.
- Terminals: Solderable per MIL-STD-750, method 2026.
- Polarity: Indicated by cathode band.
- Mounting position: Any.



Circuit Diagram



Marking:F

Maximum Rating (at TA=25°C unless otherwise noted)

Parameter	Conditions	Symbol	Limits	Unit
Reverse voltage (DC)		V_R	40	V
Average rectified forward current		I_o	100	mA
Forward current surge peak	60Hz for 1cyc	I_{FSM}	500	mA
Junction temperature		T_j	+125	°C
Storage temperature		T_{STG}	-40 to +125	°C

Electrical Characteristics (at TA=25°C unless otherwise noted)

Parameter	Conditions	Symbol	Min	Typ	Max	Unit
Forward voltage	$I_F = 10 \text{ mA}$	V_F	-	-	0.35	V
Reverse current	$V_R = 10 \text{ V}$	I_R	-	-	10	μA

Typical Electrical Characteristic Curves

Fig.1 - Forward Characteristics

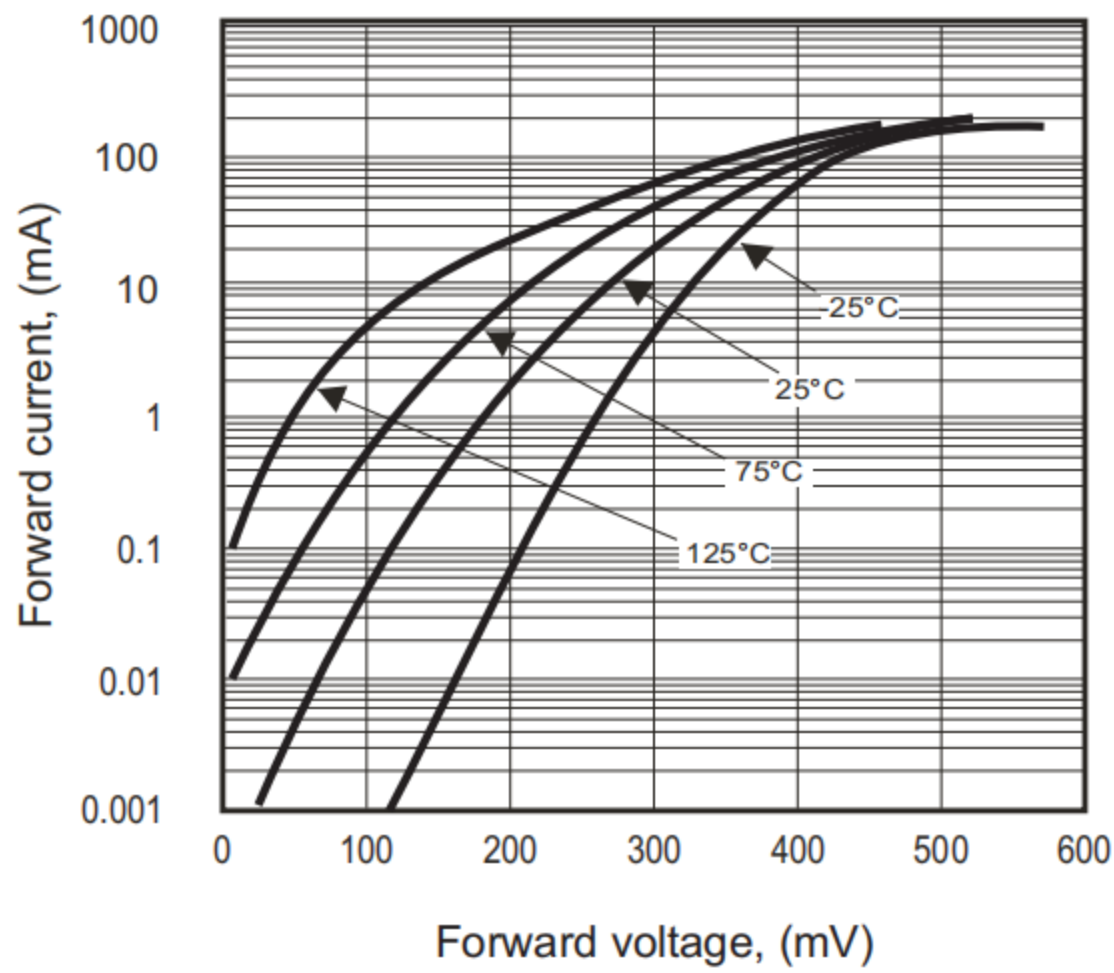


Fig.2 - Reverse Characteristics

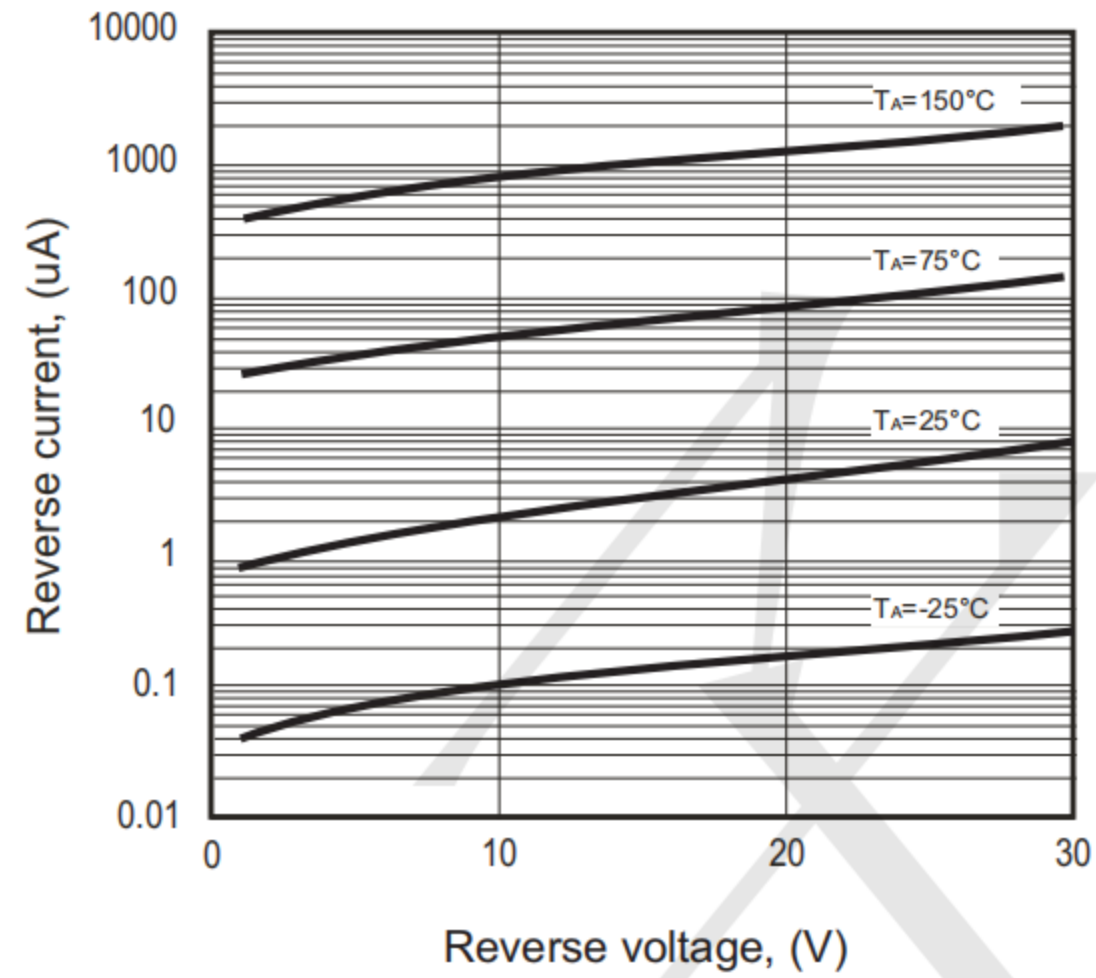


Fig.3 - Capacitance Between Terminals

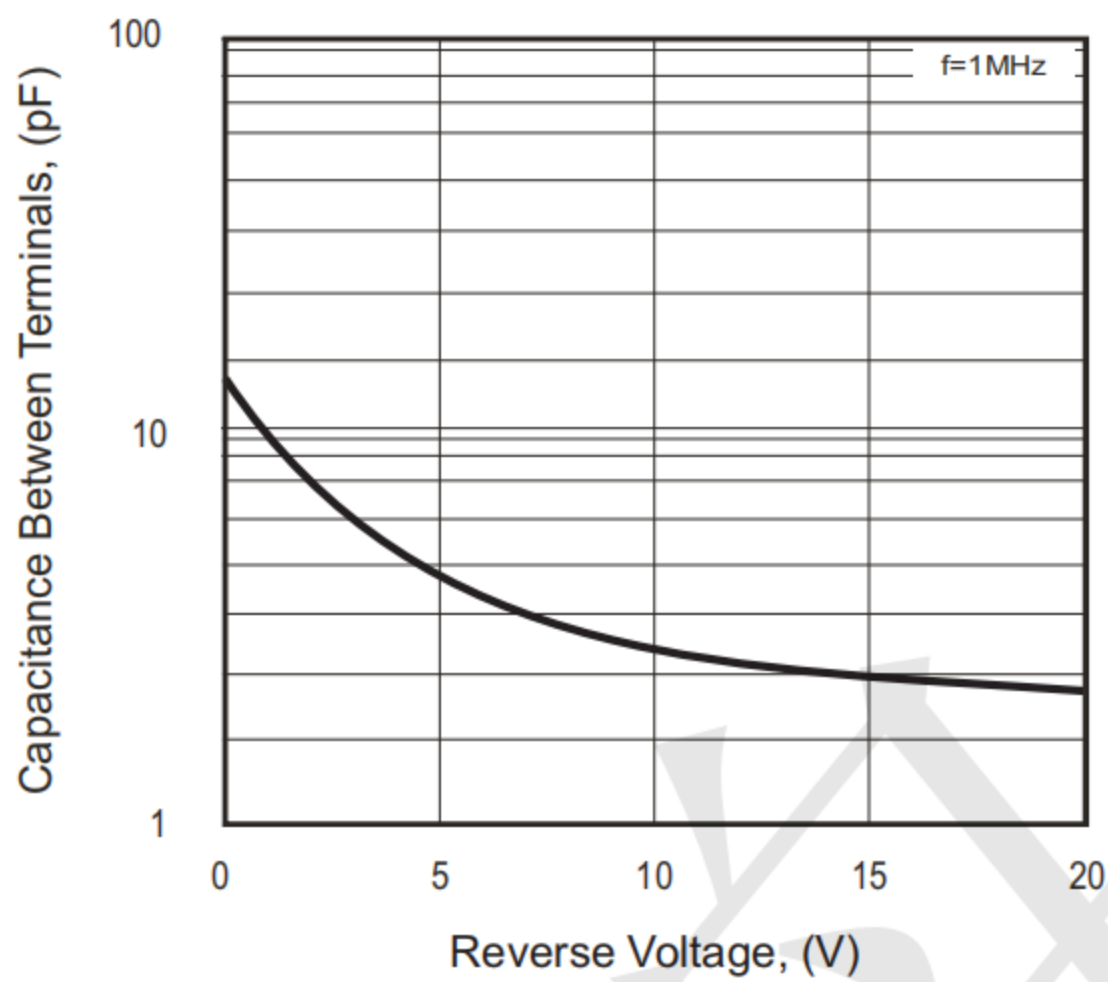


Fig.4 - IFSM-Cycle Characteristics

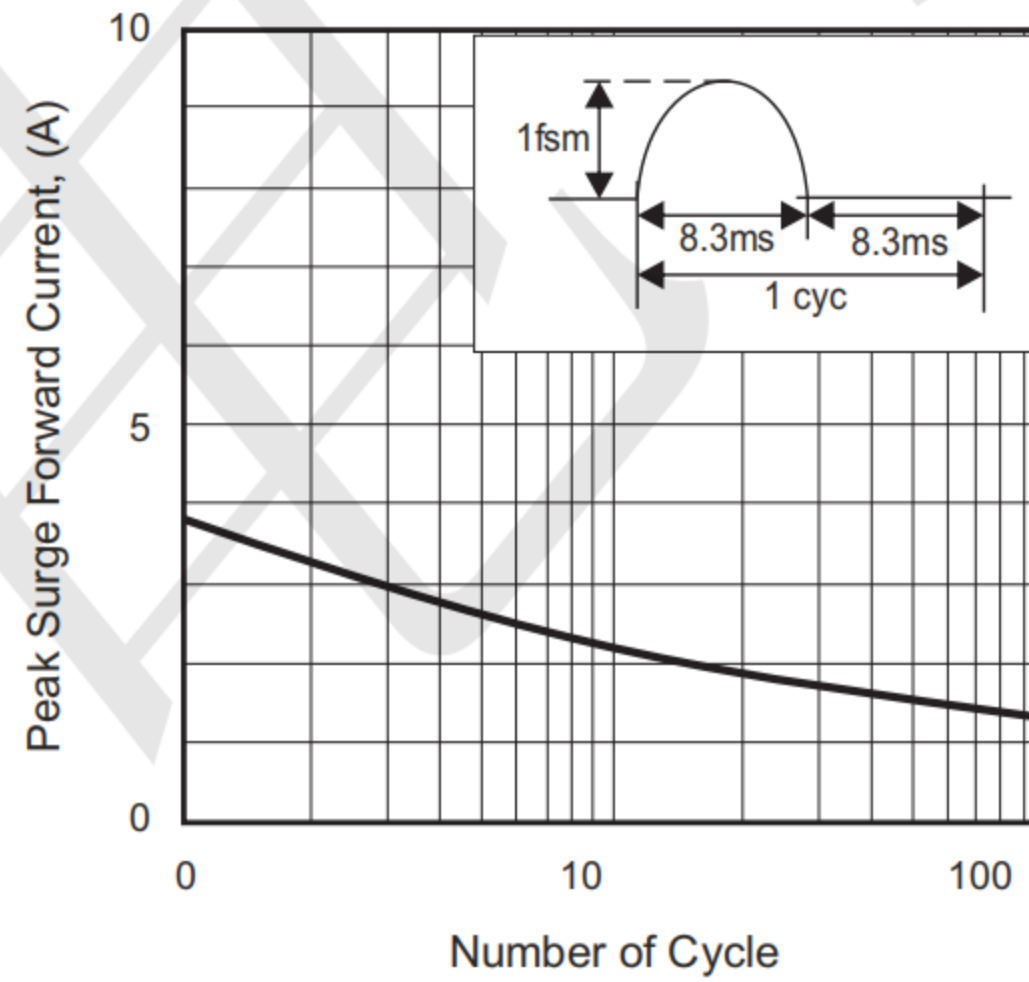
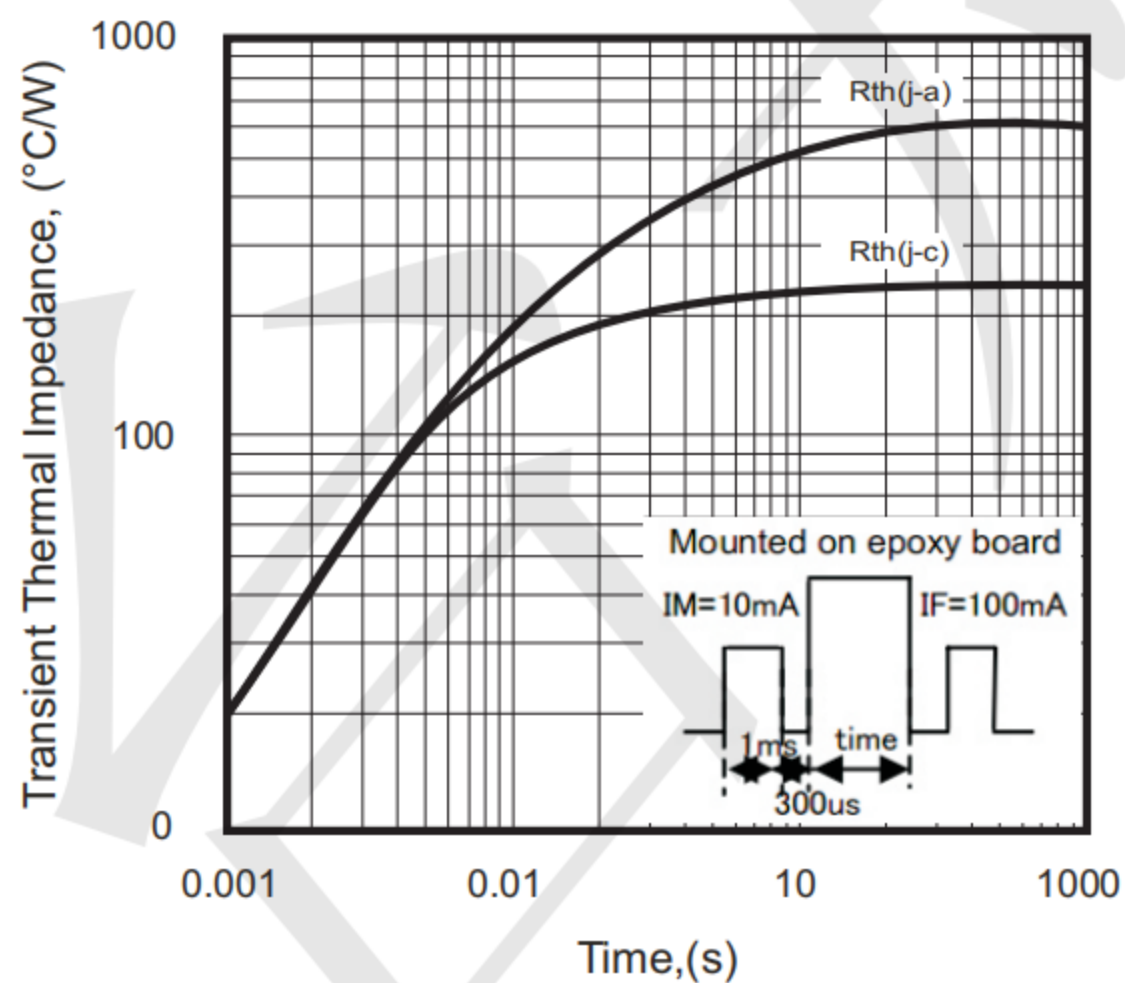
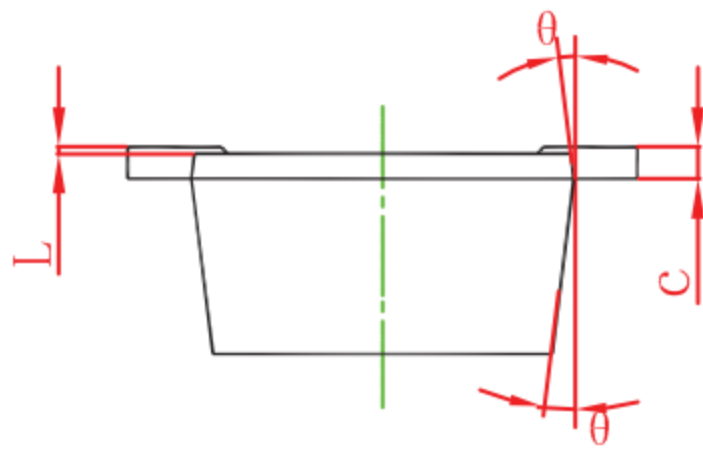
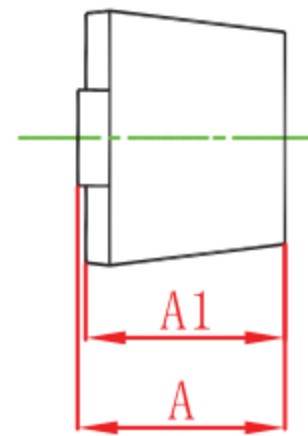
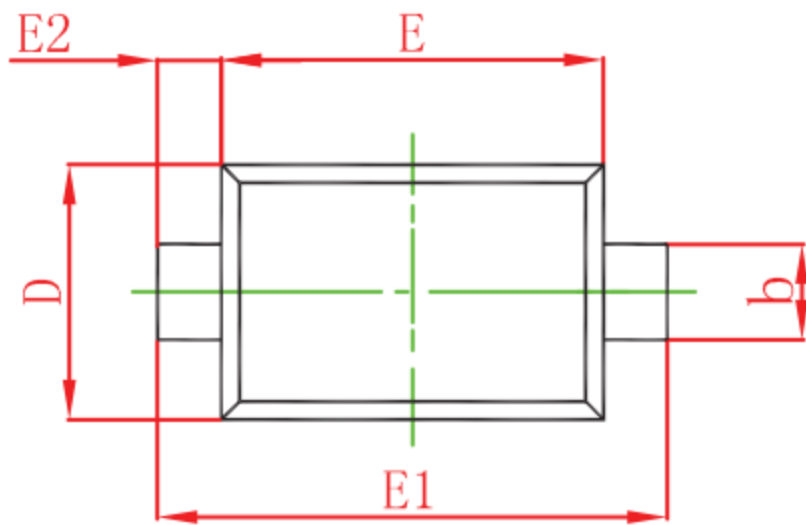


Fig.5 - Rth-t Characteristics

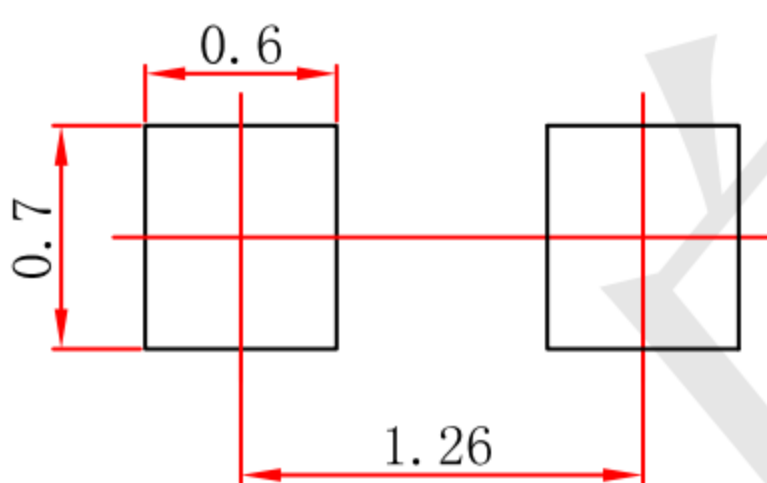


Outline Drawing - SOD-723 (unit: mm)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.525	0.650	0.021	0.026
A1	0.515	0.580	0.020	0.023
b	0.250	0.350	0.010	0.014
c	0.080	0.150	0.003	0.006
D	0.550	0.650	0.022	0.026
E	0.900	1.100	0.035	0.043
E1	1.300	1.500	0.051	0.059
E2	0.200 REF		0.008 REF	
L	0.010	0.070	0.001	0.003
θ	7° REF		7° REF	

Mounting Pad Layout-SOD723 (unit: mm)



- Note:
1. Controlling dimension: in millimeters.
 2. General tolerance: $\pm 0.05\text{mm}$.
 3. The pad layout is for reference purposes only.